

CUSTOMER DRAWING

REVISIONS

SYM	ECN	DESCRIPTION	DATE	APPROVED
1	CDXXXX	NEW RELEASE	SEP.25,2013	YH
2	CDXXXX	UPDATE DRAWING	SEP.26,2013	YH
3	CDXXXX	UPDATE DRAWING	NOV.22,2013	YH
4	CDXXXX	ADD A DIMENSION AND UPDATE DRAWING	APR.30,2014	YH



NOTE:

- MATERIAL:
PLASTIC: LCP, UL 94V-0, BLACK
CONTACT: COPPER ALLOY
BOARD LOCK: ALLOY
- FINISHED:
CONTACT AREA: SEE P/N SYSTEM
SOLDER AREA: GOLD FLASH
BOARD LOCK: TIN PLATING
UNDERPLATED: NI PLATING
- ELECTRICAL PERFORMANCE:
3.1 CURRENT RATING: 0.5A PER PIN, VOLTAGE RATING: 50 VAC PER PIN
3.2 DIELECTRIC STRENGTH: 300V AC FOR 1 MINUTE
3.3 INSULATION RESISTANCE: 500MΩ MIN
3.4 CONTACT RESISTANCE: 55mΩ MAX
3.5 OPERATION TEMPERATURE: -40°C TO +80°C
- DIMENSIONING SHALL BE INTERPRETED PER ASME Y14.5M 1994
- MATERIAL SHOULD BE FULFILLED AMPHENOL SPEC# S-SN-002
FOR HALOGEN FREE PRODUCTS, ALSO NEED TO MEET # S-SN-004

ORDER P/N SYSTEM:

MDT XXX X XX 001

CONNECTOR HEIGHT

XXX	DIM E	DIM F
580	5.80MAX	4.14MAX
420	4.20MAX	2.54MAX
320	3.20MAX	1.54MAX
275	2.75MAX	0.89MAX
245	2.45MAX	0.61MAX

PLATING

- 01 0.76 MICRONS GOLD PLATING
02 0.38 MICRONS GOLD PLATING
03 GOLD FLASH

CONNECTOR KEY ID

- A - KEY A
B - KEY B
E - KEY E
M - KEY M
...

PROPOSAL DRAWING

M	14.0	2.0	1.375	6.125	
E	5.5	10.5	1.125	-2.625	
B	2.5	13.5		-5.625	
A	1.5	14.5		-6.625	
KEY ID	DIM.A	DIM.B	DIM.C	DIM.D	REMARK

UNLESS OTHERWISE SPECIFIED
TOLERANCES

	U.S.	METRIC
.X	+/-	0.50
.XX	+/-	0.25
.XXX	+/-	
FRACTIONS	+/-	
ANGLES	+/-	5°

FOR MATERIALS AND FINISHES
SEE NOTES

REMOVE SHARP EDGES
DIMENSIONS
U.S. INCHES
(METRIC) (MM)

APPROVAL

DRAWN Yunx.liu

CHECKED LY.YI

APPROVED

DRAWING FILE :

DRAWING\MDT\CMDTXXXXXX001

DATE

APR.30,2014

APR.30,2014

ANGLE OF PROJECTION

Amphenol

TITLE

M.2 MINI PCIe CONECTOR

SIZE

A3

DRAWING NO.

C MDT-XXX-X-XX-001

REV.

4

SCALE

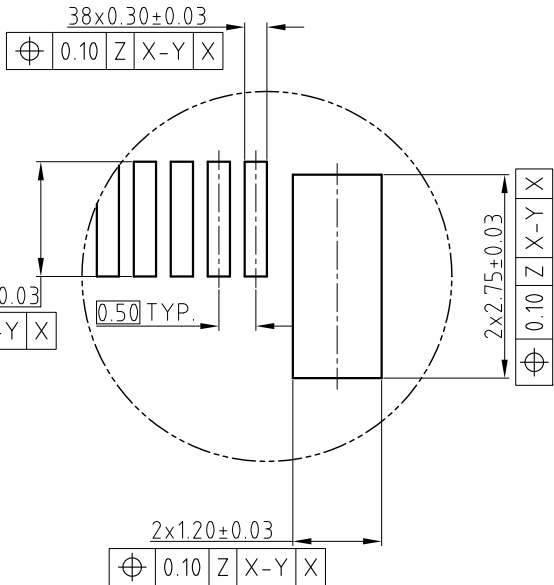
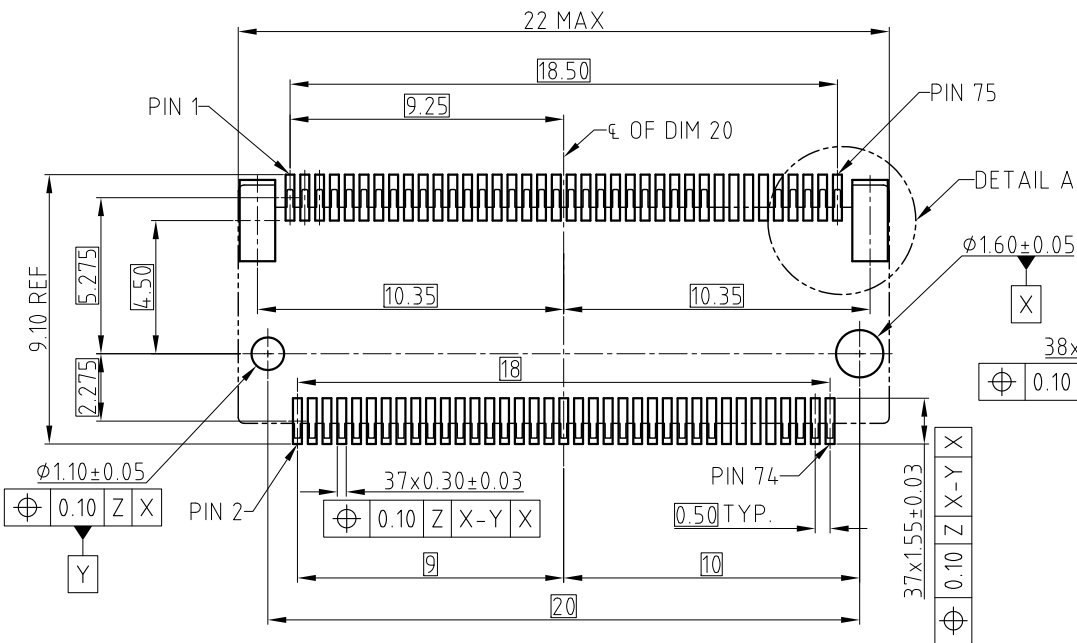
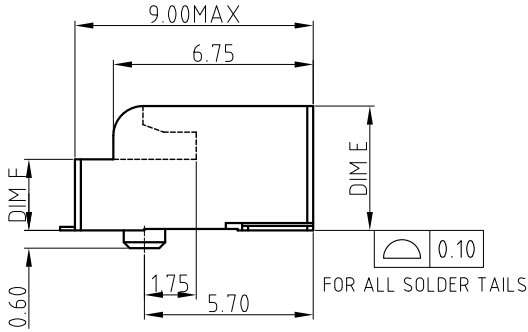
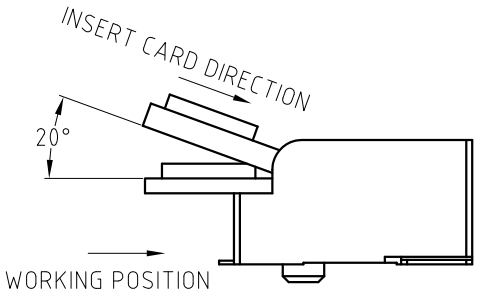
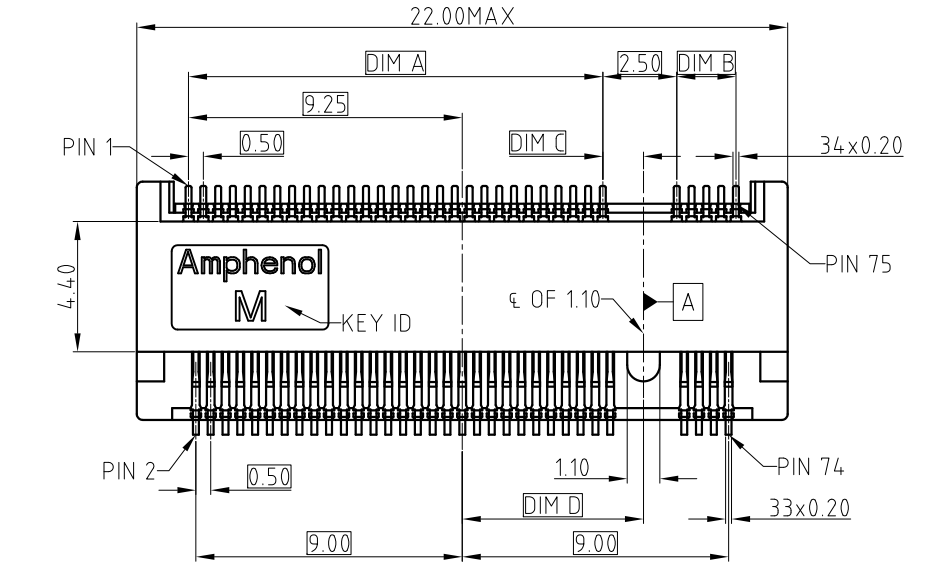
NONE

SHEET

1

OF

1



RECOMMENDED M.2 MINI CARD MOUNTING TYPE_SMT_PCB OUTLINE
DATUM Z: PCB SOLDER SURFACE

DETAIL A
SCALE 2.5:1